L Number	Hits	Search Text	DB	Time stamp
1	5291	257/666	USPAT;	2004/08/05 17:13
-			US-PGPUB;	
	· ·		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	951	257/667	USPAT;	2004/08/05 17:21
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		057.4660	IBM_TDB	0004/00/05 17-40
3.	2334	257/668	USPAT; US-PGPUB;	2004/08/05 17:40
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
4	1063	257/324	USPAT;	2004/08/05 17:51
1			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	842	257/635	USPAT;	2004/08/05 17:58
		0	US-PGPUB;	"
	,		EPO; JPO;	
			DERWENT;	
		057 /750	IBM_TDB	0004/00/05 10 01
6	4668	257/758	USPAT;	2004/08/05 18:31
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
7	2650	257/700	USPAT;	2004/08/05 18:55
'	2030	2377 700	US-PGPUB;	2001,00,03 10.03
			EPO; JPO;	
			DERWENT;	
Į į			IBM_TDB	
8	2132	438/118	USPAT;	2004/08/05 19:12
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		420 /102	IBM_TDB	2004/00/05 12 11
9	1646	438/123	USPAT;	2004/08/05 19:14
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	105	'van der waal' and 257/\$.ccls.	USPAT;	2003/03/26 13:23
	103		US-PGPUB;	2003,03,20 13.23
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	225	'van der waal' and 438/\$.ccls.	USPĀT;	2004/08/05 16:35
			US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
		1-1	IBM_TDB	0002/02/05 10 12
-	42	latex and 257/\$.ccls.	USPAT;	2003/03/25 18:10
1			US-PGPUB;	
			EPO; JPO; DERWENT;	
		1.0 4	IBM TDB	
_	53	latex and 438/\$.ccls.	USPAT;	2002/07/11 10:23
	55	Lacon and 100/4.0015.	US-PGPUB;	2002,01/11 10.23
			EPO; JPO;	
			DERWENT;	
		7 / /	IBM TDB	
-	156	self-vulcanizing latex and (copper adj	USPĀT;	2003/03/26 11:25
	- 5	layer) and interconnect and 257/\$.ccls.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

	1062	0571666	HCDAM.	2002/07/09 11:04
-	4063	257/666	USPAT; US-PGPUB;	2002/07/09 11:04
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	644	interconnect and (multichip module) and	USPAT;	2002/07/09 11:06
		(copper layer) and polyimide and	US-PGPUB;	
		257/\$.ccls.	EPO; JPO;	
			DERWENT;	
	26	(IBM_TDB	2002/07/09 14:20
_	36	interconnect and (multichip adj module) and (copper adj layer) and polyimide and	USPAT; US-PGPUB;	2002/07/09 14:20
		257/\$.ccls.	EPO; JPO;	
	Ì	23774.0013.	DERWENT;	
			IBM TDB	
-	379	257/75\$.ccls. and polymer	USPĀT;	2002/07/11 10:24
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	233	257/75\$.ccls. and polymer and interconnect	IBM_TDB USPAT;	2002/07/11 10:25
	255	2377737.ccis. and polymer and interconnect	US-PGPUB;	2002/07/11 10:23
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	10	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2002/07/12 09:28
		adhesive)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	74	438/\$.ccls. and (latex)	USPĀT;	2003/03/26 08:06
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	0.1	057/01 (1 MTMV 1-1)	IBM_TDB	2002/10/27 15:25
_	21	257/\$.ccls. and (polymer WITH latex)	USPAT; US-PGPUB;	2003/10/27 15:25
			EPO; JPO;	1
			DERWENT;	
			IBM TDB	
-	28	438/\$.ccls. and (polymer WITH latex)	USPAT;	2003/10/29 08:56
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	15	257/\$.ccls. and (adhesive WITH latex)	USPAT;	2003/10/28 17:08
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	40	438/\$.ccls. and (latex with particle)	IBM_TDB	2003/10/28 18:11
-	40	430/9.0015. and (talex with particle)	USPAT; US-PGPUB;	2003/10/20 18:11
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	86	438/\$.ccls. and (dielectric near3 rough)	USPAT;	2003/10/29 08:57
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	98	257/\$.ccls. and (dielectric near3 rough)	USPAT;	2003/10/29 09:10
		· .	US-PGPUB;	
			EPO; JPO;	
) 	DERWENT;	
	L		IBM_TDB	<u> </u>